SILICON (Si) POWER MOSFET A CEP06N7



CEP06N7

700V ▲ 1.65Ω ▲ 6A ▲ Si MOSFET

SILICON Si MOSFET ▲ THT type N-channel enhancement mode UL94V-0 rated flame retardant epoxy TO220-3L package Super high dense cell density for extremely low R_{DS(ON)} High power and current handling capability

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MAXIMUM RATINGS

Parameter (T _c = 25°C, unless otherwise noted)		Characteristics
Drain-Source Voltage	V _{DS}	700V
Gate-Source Voltage	V _{GS}	±30V
Continuous Drain Current at T _c = 25°C	Ι _D	6A
Continuous Drain Current at T _c = 100°C	Ι _D	4A
Pulsed Drain Current Note 1	IDM ^{Note 4}	24A
Maximum Power Dissipation at T _c = 25°C	PD	150W
Power Dissipation Derating above 25°C	ΔP _D	1W/°C
Single Pulsed Avalanche Energy Note 5	E _{AS}	125mJ
Single Pulsed Avalanche Current Note 5	I _{AS}	5A
Operating and Storage Temperature Range	T _J , T _{STG}	-55°C to +175°C

THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case	R _{TH_JC}	1°C/W
Thermal Resistance, Junction-to-Ambient	R _{TH_JA}	62.5°C/W

APPLICATIONS



PIN DESCRIPTION

Circuit Diagram	Outline • Front View	Pin No.	Description
G (1)		1	Gate
G (1)		2	Drain
S (3)		3	Source

CEP06N7 ▲ Rev.001 ▲ Date: 30/09/2022 ▲ Page: 1

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ELECTRICAL CHARACTERISTICS A T_c = 25°C, unless otherwise noted

ltem	Condition	Symbol	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 250\mu A$	BV _{DSS}	700			V
Zero Gate Voltage Drain Current	V_{DS} = 700V, V_{GS} = 0V	I _{DSS}			1	μΑ
Gate Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	I _{GSSF}			100	nA
Gate Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	I _{GSSR}			-100	nA
On Characteristics Note 2						
Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250 \mu A$	V _{GS(th)}	2		4	V
Static Drain-Source On-Resistance	$V_{GS} = 10V$, $I_D = 3A$	R _{DS(ON)}		1.65	2	Ω
Gate Input Resistance	f = 1MHz, Open Drain	R _G		2		Ω
Dynamic Characteristics Note 3						
Input Capacitance	V_{DS} = 25V, V_{GS} = 0V, f = 1MHz	CISS		1130		рF
Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V, f = 1MHz$	Coss		115		pF
Reverse Transfer Capacitance	V_{DS} = 25V, V_{GS} = 0V, f = 1MHz	C _{RSS}		20		pF
Switching Characteristics Note 3						
Turn-On Delay Time	V_{DD} = 560V, V_{GS} = 10V, I_D = 5A, $R_{G(ext)}$ = 25 Ω	t _{D(ON)}		30		ns
Turn-On Rise Time	V_{DD} = 560V, V_{GS} = 10V, I_D = 5A, $R_{G(ext)}$ = 25 Ω	t _R		41		ns
Turn-Off Delay Time	V_{DD} = 560V, V_{GS} = 10V, I_{D} = 5A, $R_{\text{G(ext)}}$ = 25 Ω	t _{D(OFF)}		77		ns
Turn-Off Fall Time	V_{DD} = 560V, V_{GS} = 10V, I_{D} = 5A, $R_{\text{G(ext)}}$ = 25 Ω	t _F		42		ns
Total Gate Charge	$V_{DS} = 560V, V_{GS} = 10V, I_D = 5A$	Q _G		23		nC
Gate Source Charge	$V_{DS} = 560V, V_{GS} = 10V, I_D = 5A$	Q _{GS}		5		nC
Gate Drain Charge	V_{DS} = 560V, V_{GS} = 10V, I_{D} = 5A	\mathbf{Q}_{GD}		8		nC
Drain-Source Diode Characteristics a	nd Maximum Ratings					
Drain-Source Diode Forward Current		Is			6	А
Drain-Source Diode Forward Voltage Note 2	V_{GS} = 0V, I_S = 6A	V_{SD}			1.5	V

Notes

1: Repetitive Rating: Pulse width limited by maximum junction temperature

2: Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

3: Guaranteed by design, not subject to production testing.

4: Pulse width limited by safe operating area.

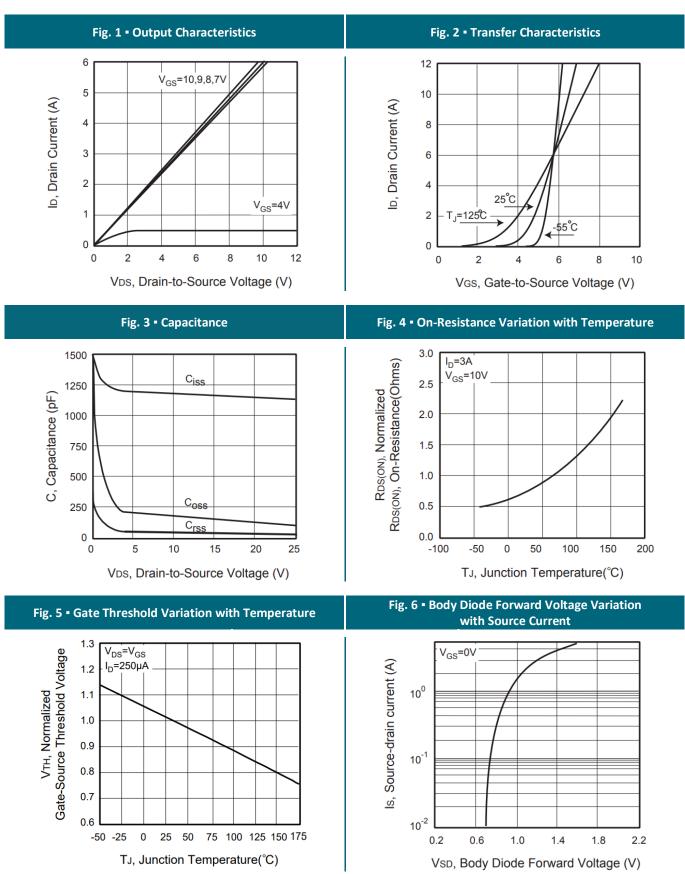
5: L = 6mH, I_{AS} = 3.6A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25°C.



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REFERENCE DATA ▲ TYPICAL DEVICE PERFORMANCE



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REFERENCE DATA ▲ TYPICAL DEVICE PERFORMANCE

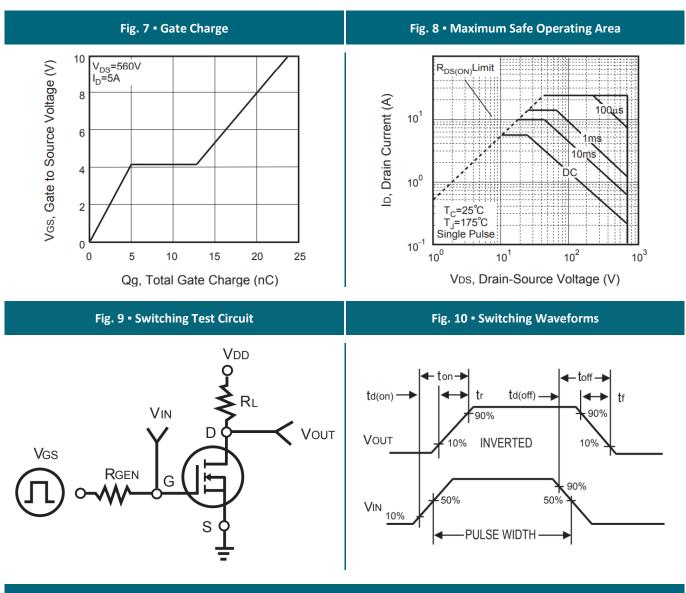
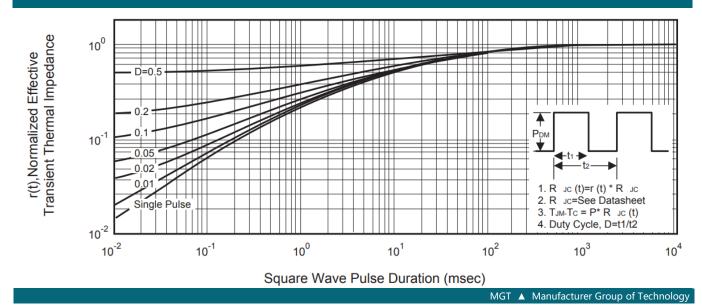


Fig. 11 • Normalized Thermal Transient Impedance Curve

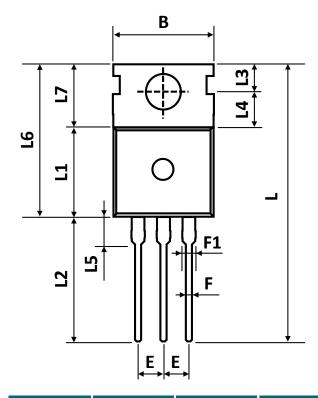


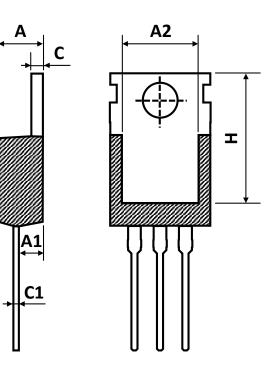
CEP06N7 ▲ Rev.001 ▲ Date: 30/09/2022 ▲ Page: 4

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PACKAGE OUTLINE





Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
А	4.43	4.53	4.63
A1	2.30	2.40	2.50
A2	7.70	7.90	8.10
В	9.80	10.00	10.20
С	1.25	1.30	1.40
C1	0.45	0.50	0.60
D	3.45	3.60	3.70
E	2.45	2.54	2.60
F	0.70	0.80	0.95
F1	1.15	1.33	1.50
L	26.80	28.80	30.80
L1	9.20	9.30	9.40
L2	12.80	13.10	13.40
L3	2.70	2.80	2.90
L4	3.50	3.70	3.80
L5	2.60	2.90	3.20
L6	15.40	15.80	16.20
L7	6.20	6.50	6.80
Н	12.95	13.25	13.55

ORDERING INFORMATION

Part Number	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
CEP06N7	TO-220-3L	Tube	50pcs	1,000pcs	4,000pcs
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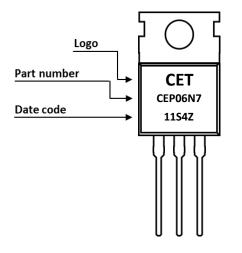
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PART MARKING



DATE CODE

Example: 11S4Z



| Product Type Z: Pb-free G: Green Product

	Coding list for "Day"								
1	2	3	4	5	6	7	8	9	A
01	02	03	04	05	06	07	08	09	10
B	C	D	E	F	G	H	 	J	K
11	12	13	14	15	16	17	18	19	20
L	M	N	O	P	Q	R	S	T	U
21	22	23	24	25	26	27	28	29	30
V 31									

Coding list for "Month"

1 Jan	2 Feb		5 May	
7	8	A	B	C
Jul	Aug	Oct	Nov	Dec

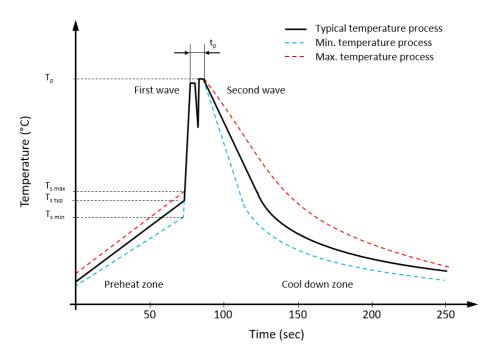
Coding list for "Year"







RECOMMENDED WAVE SOLDERING PROFILE ▲ THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value 🛦 Sn-Pb Assembly	Value 🔺 Pb-free Assembly
Preheat temperature min.	$T_{s min}$	100 °C	100 °C
Preheat temperature typical	T _{s typ}	120 °C	120 °C
Preheat temperature max.	$T_{s max}$	130 °C	130 °C
Preheat time t_s from $T_{s min}$ to $T_{s max}$	ts	70 seconds	70 seconds
Peak temperature	Tp	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	t _p	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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